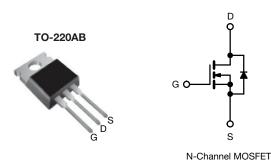
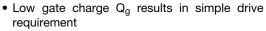
Vishay Siliconix

## **Power MOSFET**



PRODUCT SUMMARY				
V <sub>DS</sub> (V)	500			
$R_{DS(on)}(\Omega)$	V <sub>GS</sub> = 10 V 0.21			
Q <sub>g</sub> max. (nC)	110			
Q <sub>gs</sub> (nC)	33			
Q <sub>gd</sub> (nC)	54			
Configuration	Single			

### **FEATURES**





• Improved gate, avalanche, and dynamic dV/dt ruggedness

- RoHS\*
- Fully characterized capacitance and avalanche voltage and current
- Low R<sub>DS(on)</sub>
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912">www.vishav.com/doc?99912</a>

### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

### **APPLICATIONS**

- Switch mode power supply (SMPS)
- Uninterruptible power supply
- · High speed power switching
- · Hard switched and high frequency circuits

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRFB20N50KPbF

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V <sub>DS</sub>	500		
Gate-source voltage			$V_{GS}$	± 30	V	
Continuous drain current	V <sub>GS</sub> at 10 V	$T_{\rm C} = 25  ^{\circ}{\rm C}$ $T_{\rm C} = 100  ^{\circ}{\rm C}$	1_	20	А	
Continuous drain current		T <sub>C</sub> = 100 °C	l <sub>D</sub>	12		
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	80	1	
Linear derating factor				2.2	W/°C	
Single pulse avalanche energy b			E <sub>AS</sub>	330	mJ	
Repetitive avalanche current a			I <sub>AR</sub>	20	Α	
Repetitive avalanche energy <sup>a</sup>			E <sub>AR</sub>	28	mJ	
Maximum power dissipation $T_C = 25  ^{\circ}C$		P <sub>D</sub>	280	W		
Peak diode recovery dV/dt <sup>c</sup>			dV/dt	10	V/ns	
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	00	
Soldering recommendations (peak temperature) <sup>d</sup>	For 10 s			300	°C	
Mounting torque	6-32 or M3 screw			10	N	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. Starting  $T_J$  = 25 °C, L = 1.6 mH,  $R_g$  = 25  $\Omega,\,I_{AS}$  = 20 A
- c.  $I_{SD} \le 20 \text{ A}$ ,  $dI/dt \le 350 \text{ A/}\mu\text{s}$ ,  $V_{DD} \le V_{DS}$ ,  $T_J \le 150 \,^{\circ}\text{C}$
- d. 1.6 mm from case



Vishay Siliconix

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum junction-to-ambient	R <sub>thJA</sub>	-	58			
Case-to-sink, flat, greased surface	R <sub>thCS</sub>	0.50	-	°C/W		
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	0.45			

PARAMETER	SYMBOL	TES	ST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static					I.	·	·
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub>	= 0 V, I <sub>D</sub> = 250 μA	500	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	ce to 25 °C, I <sub>D</sub> = 1 mA	-	0.61	-	V/°C
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3.0	-	5.0	V
Gate-source leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ± 30 V		-	-	± 100	nA
7		V <sub>DS</sub> =	= 500 V, V <sub>GS</sub> = 0 V	-	-	50	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 400 \	/, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	250	μΑ
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 12 A <sup>b</sup>	-	0.21	0.25	Ω
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 12 A		11	-	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 V$ ,		-	2870	-	
Output capacitance	C <sub>oss</sub>	1	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$		320	-	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1	.0 MHz, see fig. 5	-	34	-	pF
Outrat considerate	C <sub>oss</sub>		V <sub>DS</sub> = 1.0 V, f = 1.0 MHz	-	3480	-	
Output capacitance		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 400 V, f = 1.0 MHz	-	85	-	
Effective output capacitance	C <sub>oss</sub> eff.		V <sub>DS</sub> = 0 V to 400 V	-	160	-	
Total gate charge	Qg			-	-	110	
Gate-source charge	$Q_{gs}$	V <sub>GS</sub> = 10 V	$I_D = 20 \text{ A}, V_{DS} = 400 \text{ V}$ see fig. 6 and 13 b	-	-	33	nC
Gate-drain charge	Q <sub>gd</sub>	1	see lig. o and 15	-	-	54	
Turn-on delay time	t <sub>d(on)</sub>			-	22	-	
Rise time	t <sub>r</sub>	V <sub>DD</sub> :	= 250 V, I <sub>D</sub> = 20 A	-	74	-	
Turn-off delay time	t <sub>d(off)</sub>	$R_g = 7.5 \Omega$ , $V_{GS} = 10 V$ , see fig. 10 b - 45 -		ns			
Fall time	t <sub>f</sub>			-	33	-	
Gate input resistance	$R_g$	f = 1	MHz, open drain	0.3	-	2.9	Ω
Drain-Source Body Diode Characteristic							•
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	20	_
Pulsed diode forward current <sup>a</sup>	I <sub>SM</sub>			80	A		
Body diode voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C	C, I <sub>S</sub> = 20 A, V <sub>GS</sub> = 0 V b	-	-	1.5	V
Body diode reverse recovery time	t <sub>rr</sub>	T 05.00 !	00 A :II/:II	-	520	780	ns
Body diode reverse recovery charge	Q <sub>rr</sub>	$I_J = 25 ^{\circ}\text{C}, I_F$	= 20 A, $dI/dt = 100 A/\mu s^b$	-	5.3	8.0	μC
Forward turn-on time	t <sub>on</sub>	Intrinsic tu	urn-on time is negligible (turn	on is dor	ninated b	v I e and	[P]

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. Pulse width  $\leq$  400 µs; duty cycle  $\leq$  2 %



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

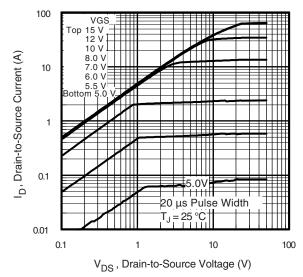


Fig. 1 - Typical Output Characteristics

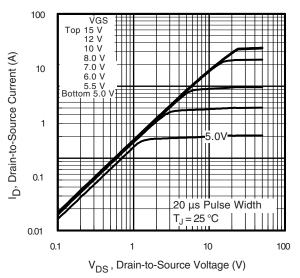


Fig. 2 - Typical Output Characteristics

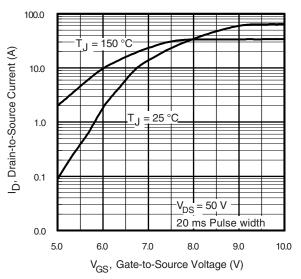


Fig. 3 - Typical Transfer Characteristics

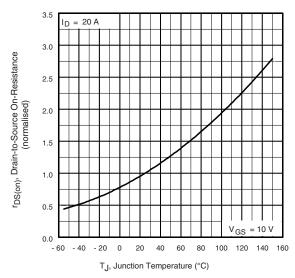


Fig. 4 - Normalized On-Resistance vs. Temperature



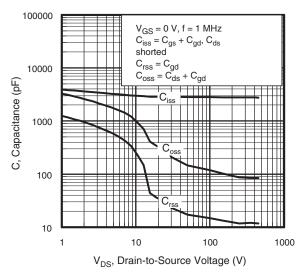


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

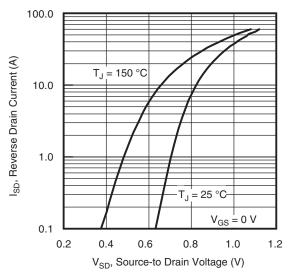


Fig. 7 - Typical Source-Drain Diode Forward Voltage

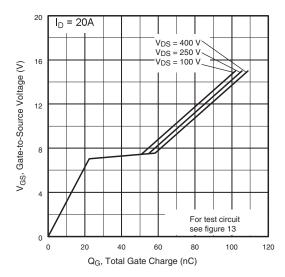


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

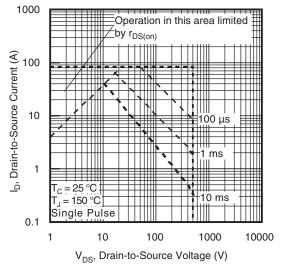


Fig. 8 - Maximum Safe Operating Area



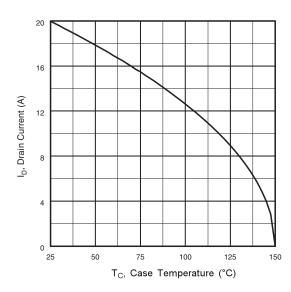


Fig. 9 - Maximum Drain Current vs. Case Temperature

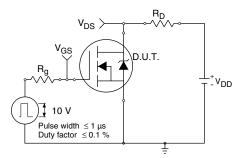


Fig. 10a - Switching Time Test Circuit

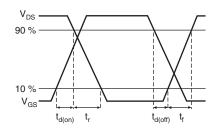


Fig. 10b - Switching Time Waveforms

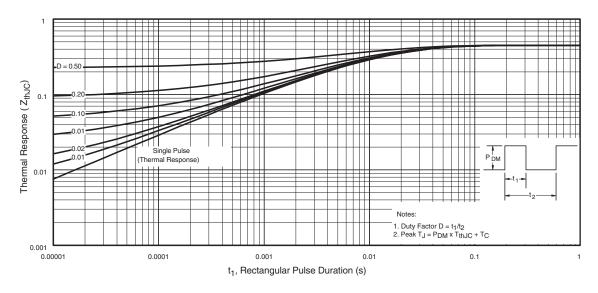


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

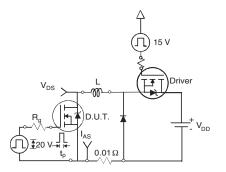


Fig. 12a - Unclamped Inductive Test Circuit

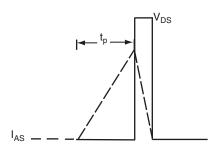


Fig. 12b - Unclamped Inductive Waveforms

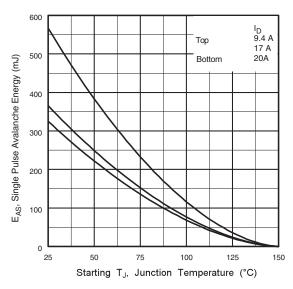


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

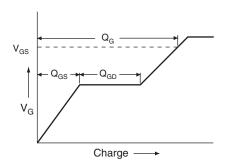


Fig. 13a - Basic Gate Charge Waveform

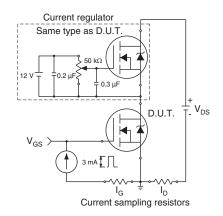
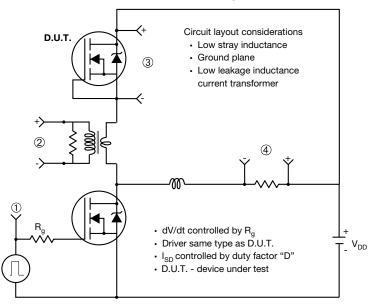


Fig. 13b - Gate Charge Test Circuit



## Peak Diode Recovery dV/dt Test Circuit



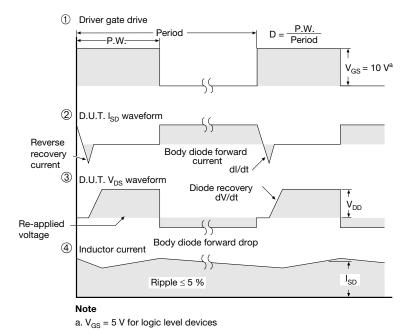


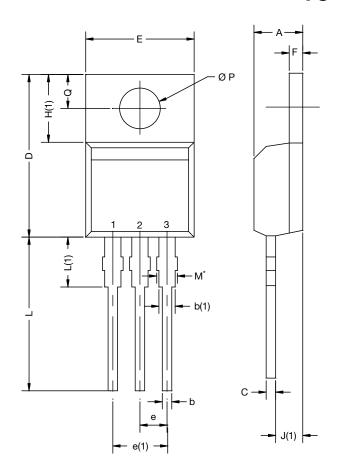
Fig. 14 - For N-Channel

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## TO-220-1



DIM.	MILLIN	METERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	

### Note

 $\bullet$   $M^{\star}=0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



Revison: 14-Dec-15 1 Document Number: 66542



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